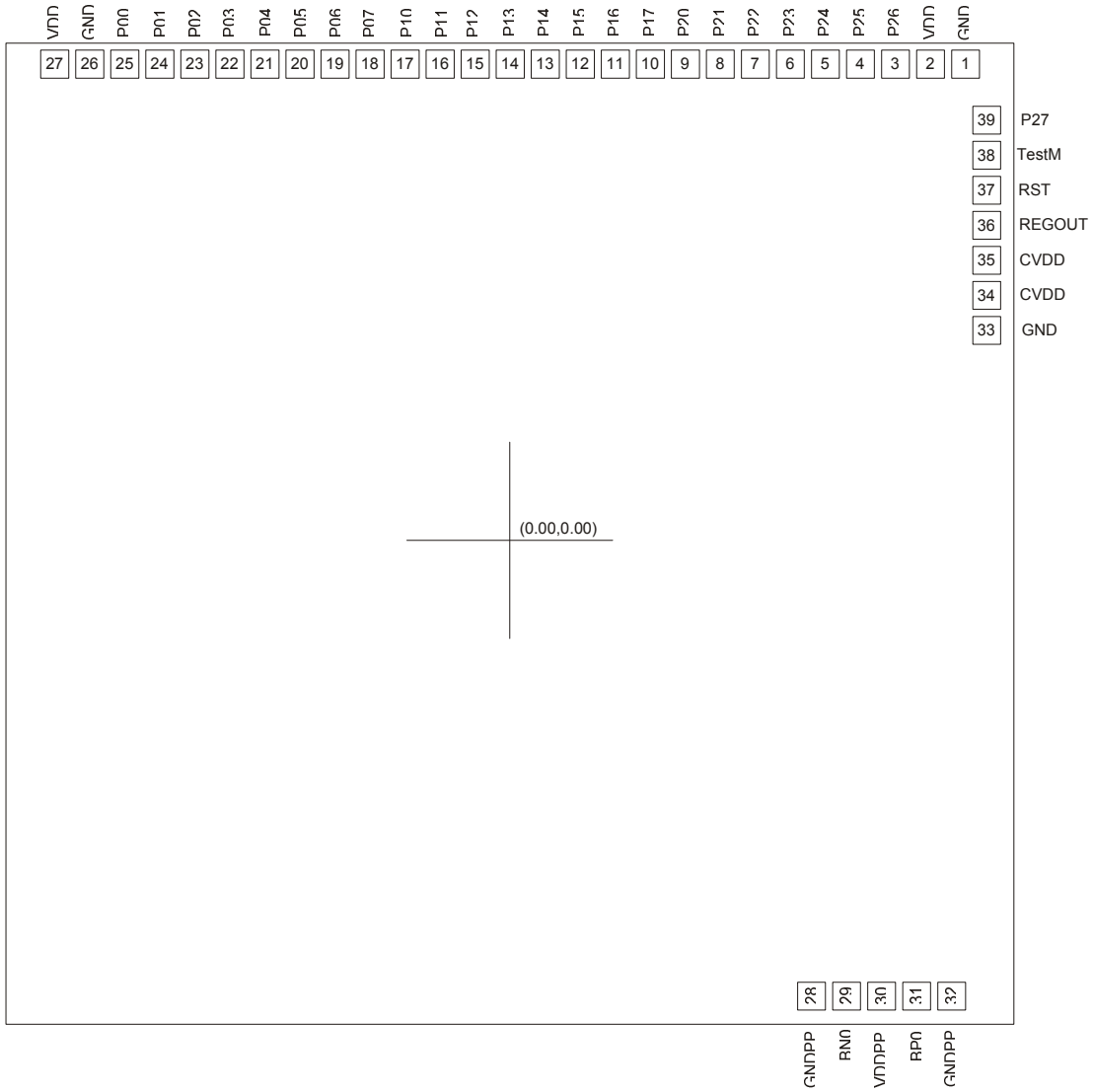




**PROJECT: SNC82300B**

NO	PAD NAME	X (um)	Y (um)	NO	PAD NAME	X (um)	Y (um)
1	GND	1395.20	1414.21	25	P00	-1244.81	1414.21
2	VDD	1285.20	1414.21	26	GND	-1354.81	1414.21
3	P26	1175.20	1414.21	27	VDD	-1464.81	1414.21
4	P25	1065.20	1414.21	28	GNDPP	887.86	-1375.00
5	P24	955.20	1414.21	29	BN0	997.86	-1375.00
6	P23	845.20	1414.21	30	VDDPP	1158.55	-1375.00
7	P22	735.20	1414.21	31	BP0	1319.26	-1375.00
8	P21	625.20	1414.21	32	GNDPP	1429.26	-1375.00
9	P20	515.20	1414.21	33	GND	1503.91	300.97
10	P17	405.19	1414.21	34	CVDD	1503.91	410.97
11	P16	295.19	1414.21	35	CVDD	1503.91	547.12
12	P15	185.19	1414.21	36	REGOUT	1503.91	654.20
13	P14	75.19	1414.21	37	RST	1503.91	892.49
14	P13	-34.81	1414.21	38	TestM	1503.91	1025.72
15	P12	-144.81	1414.21	39	P27	1503.91	1135.72
16	P11	-254.81	1414.21				
17	P10	-364.81	1414.21				
18	P07	-474.81	1414.21				
19	P06	-584.80	1414.21				
20	P05	-694.80	1414.21				
21	P04	-804.80	1414.21				
22	P03	-914.80	1414.21				
23	P02	-1024.80	1414.21				
24	P01	-1134.81	1414.21				



## SNC82300B

CHIP SIZE: X=3113um, Y=2934um

Note: The substrate MUST be connected to GND in PCB layout.